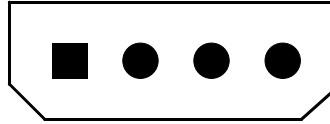




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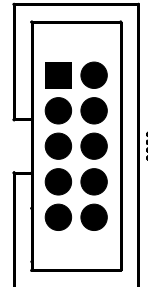
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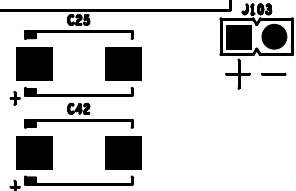
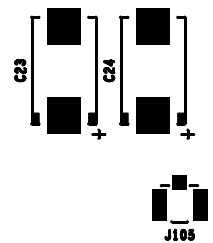
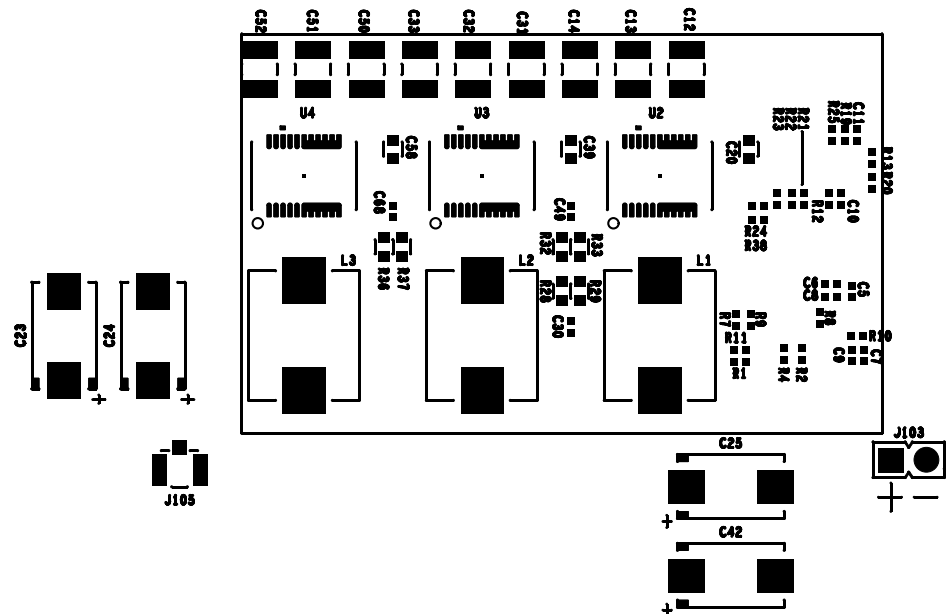
VIN GND



J104
EN



J106



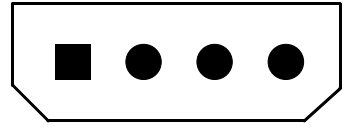
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J107

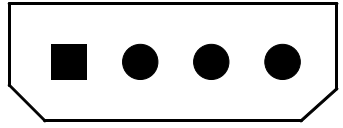
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J101

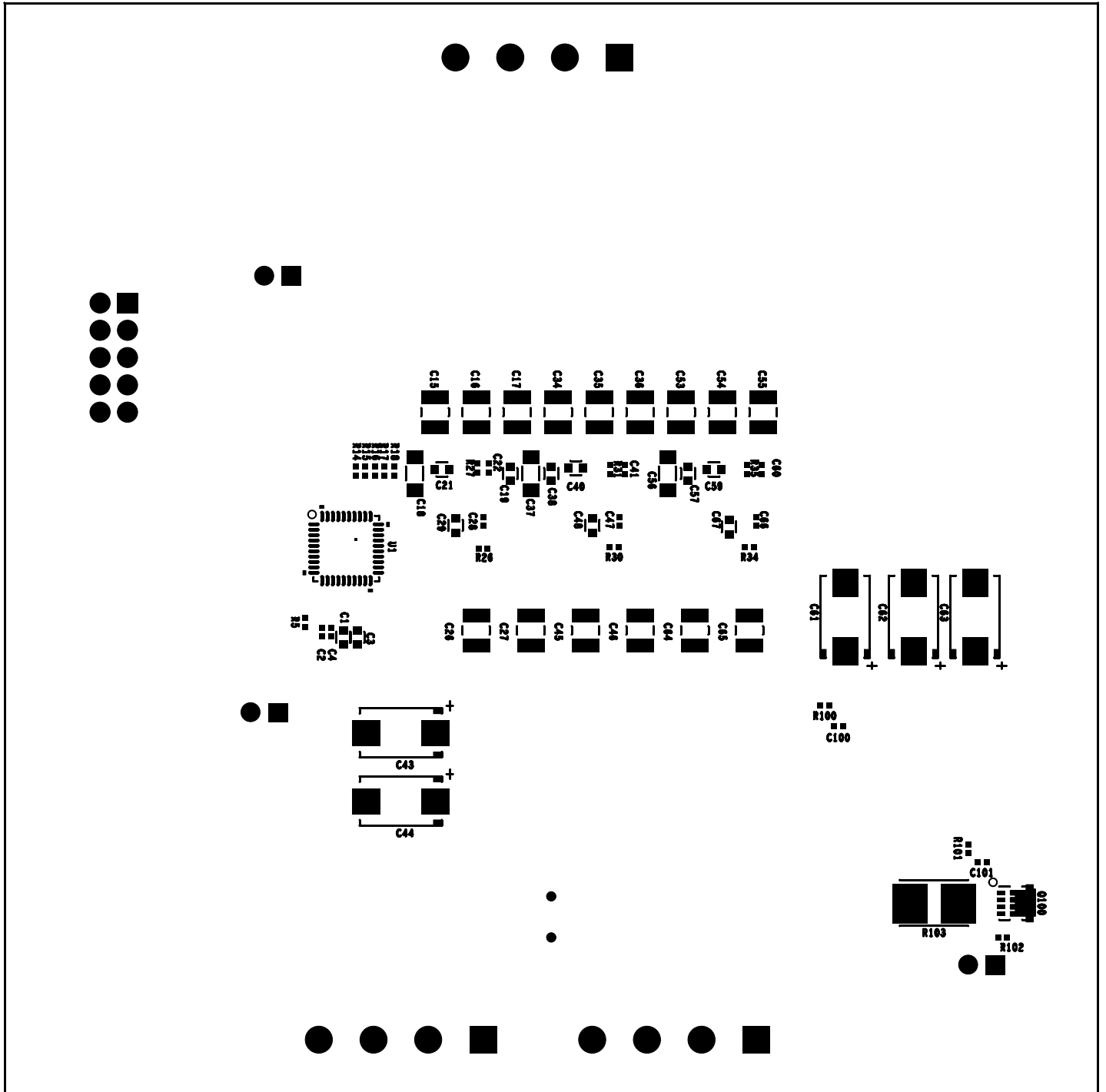


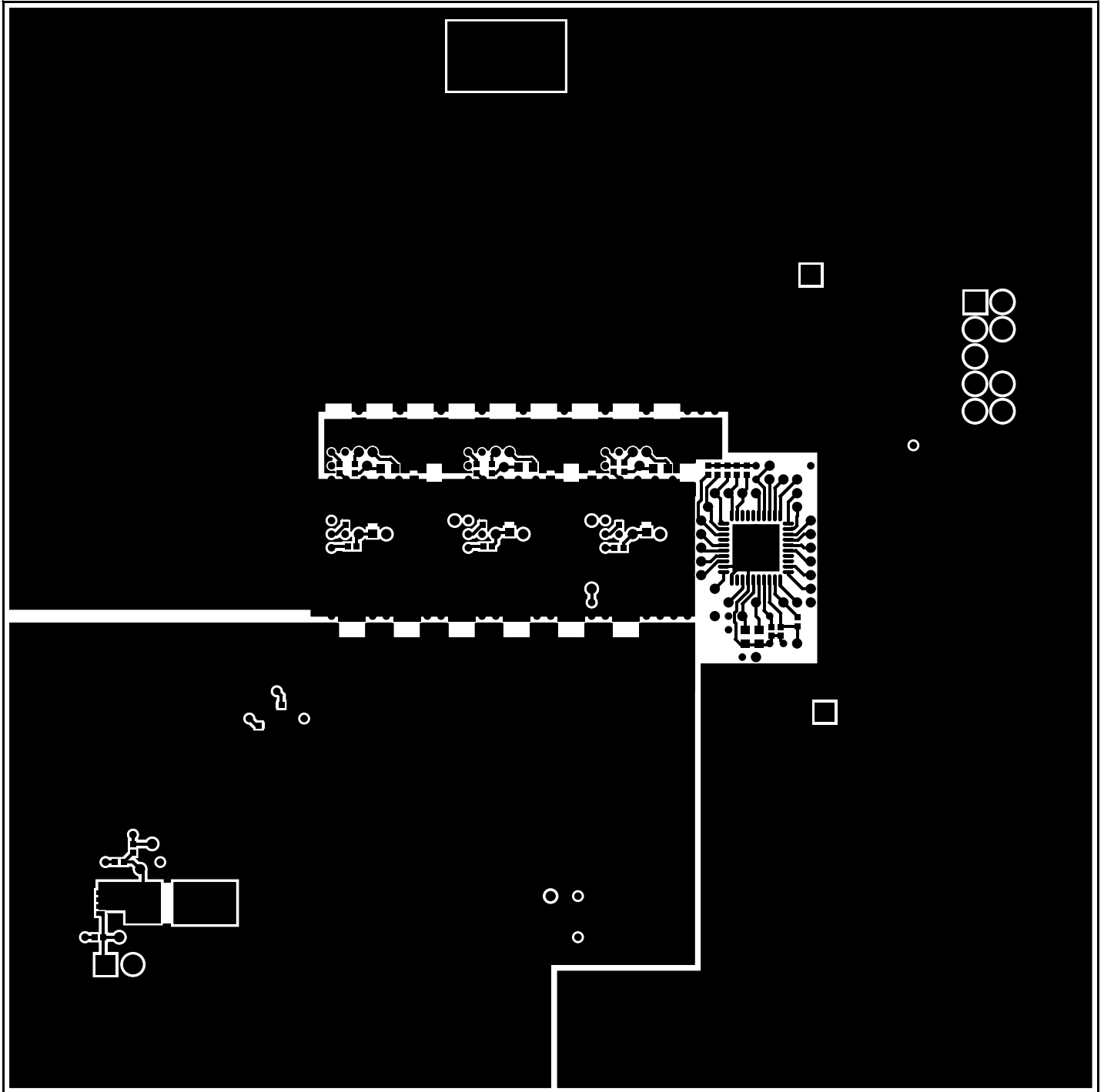
GND

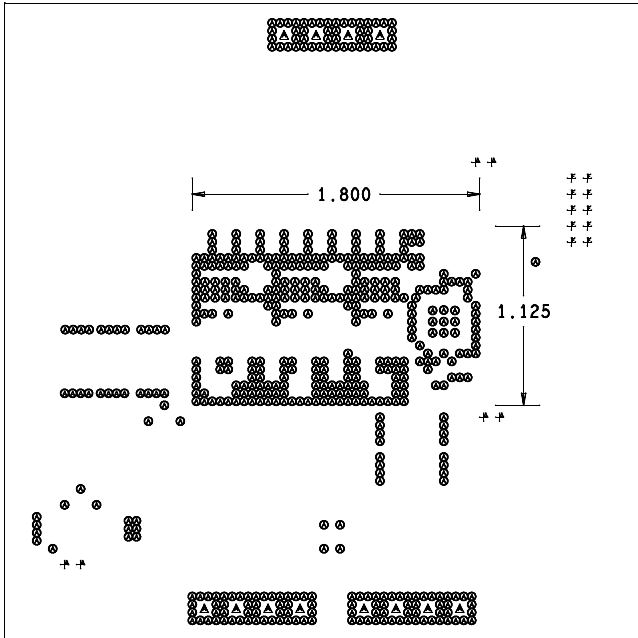
J102



PMP10962
REV A





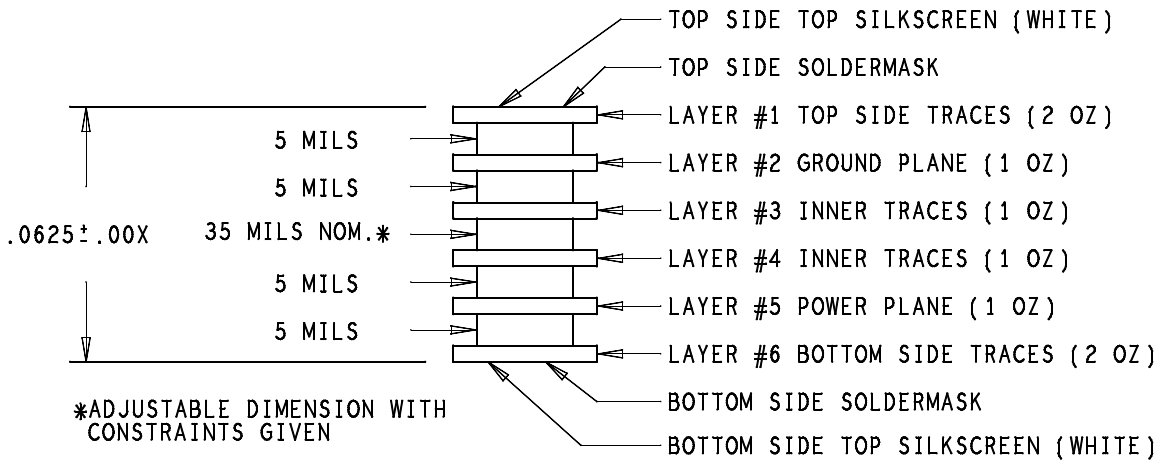


FABRICATION PARAMETERS:

THICKNESS: 0.005
 SILKSCREEN: BOTH
 SOLDERMASK: BOTH
 COPPER WEIGHT: 2 OZ (EXT) / 1 OZ (INT)
 DESIGN TYPE: N/A
 NET TRACE/WAP: 0.009/0.005
 LAYER COUNT: 6 LAYERS

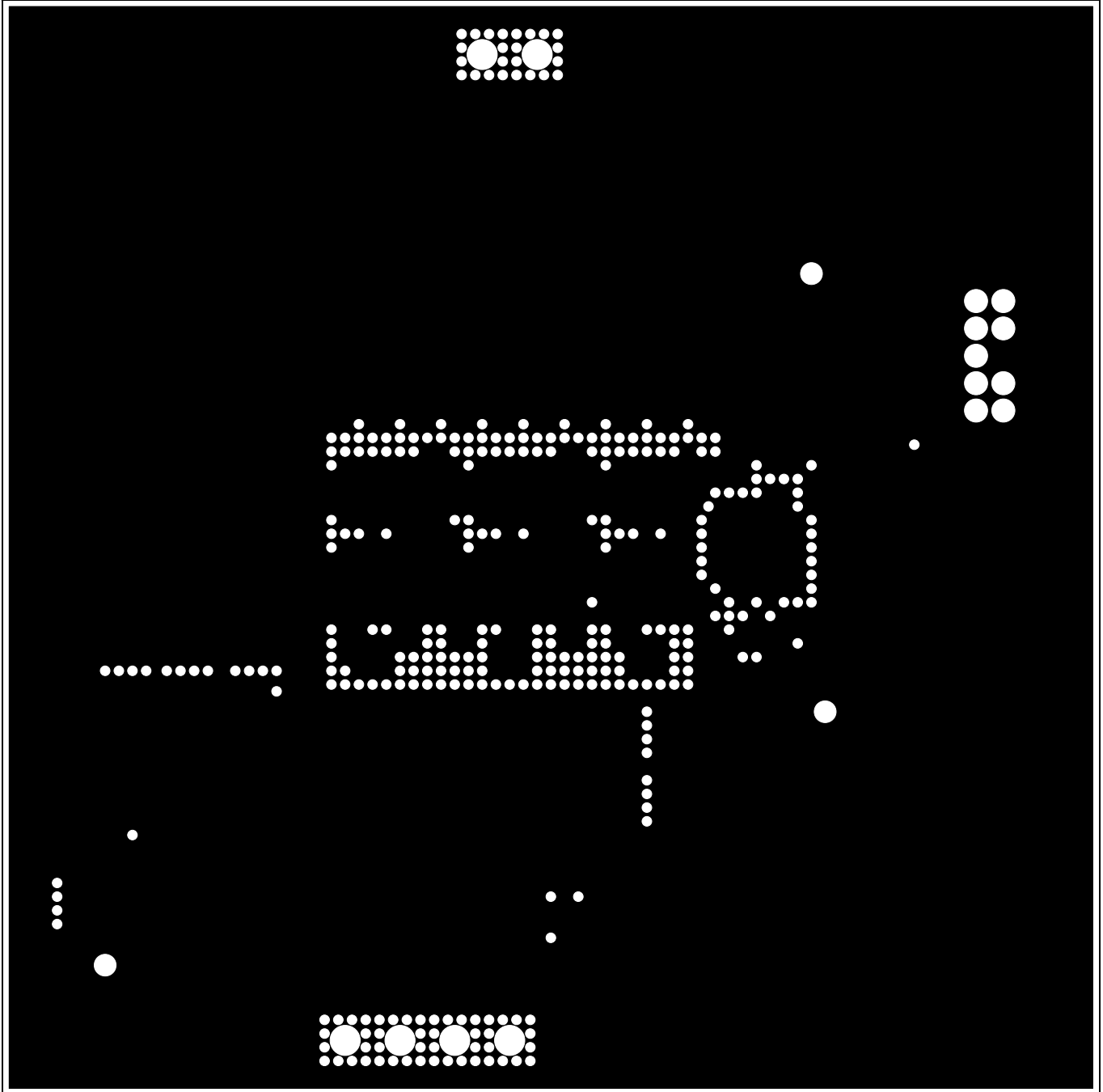
NOTES: UNLESS OTHERWISE SPECIFIED

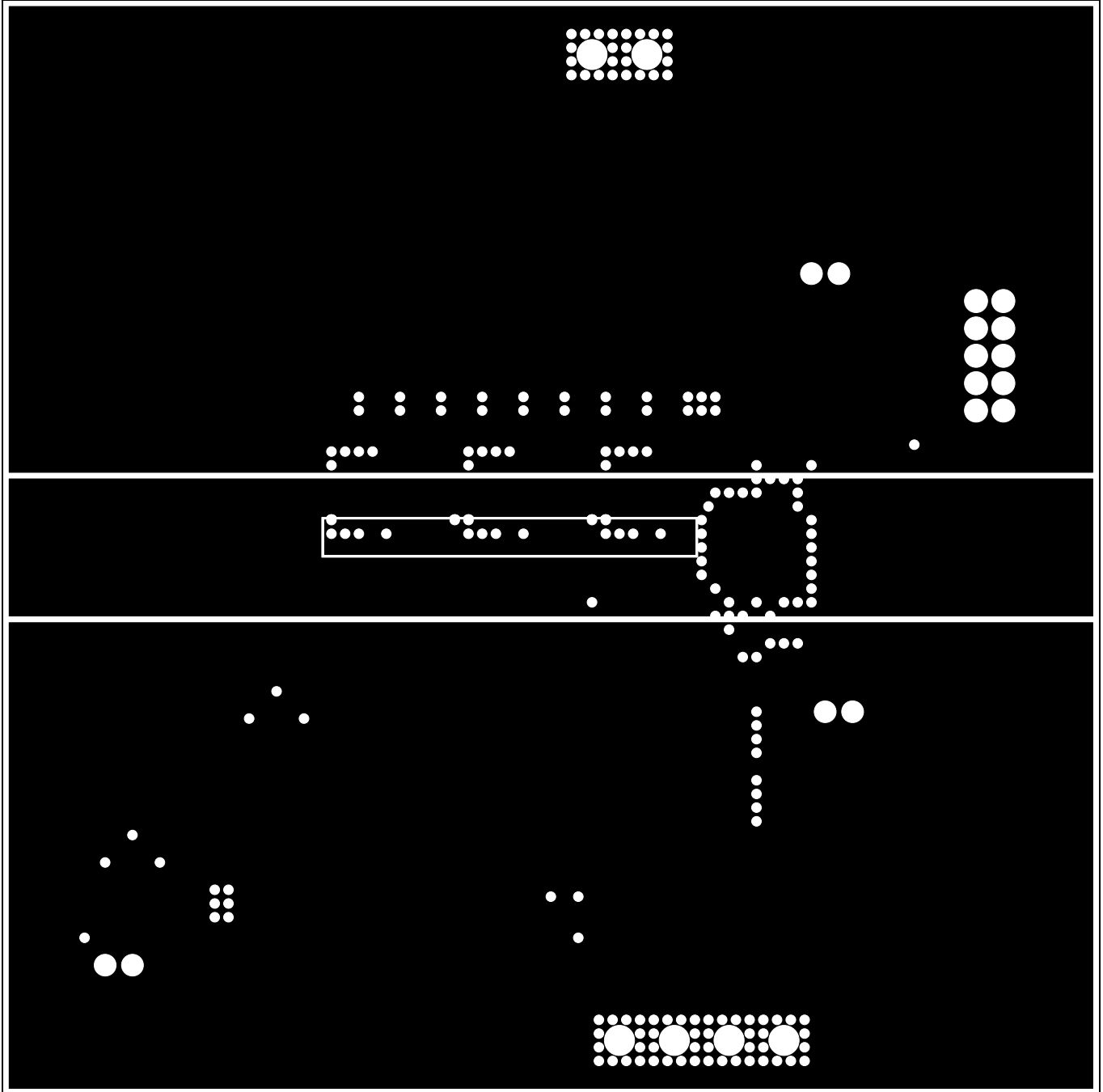
1. MATERIALS: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-709 REQUIREMENTS AND BE FULLY COMPLIANT AND HAVE A PLIABILITY OF 0.40Y-0. PLASTIC SHEET, LAMINATED METAL CLAD, TOP SIDE, BASE MATERIAL NON-TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 8 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
2. BASE LAMINATE: SOLDERMASK OVER BASE COPPER (SMBG) USING LIQUID PHOTO-IMAGABLE SOLDERMASK IN ACCORDANCE WITH IPC-3484B.
3. SOLDERMASK: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK. MIN. THICK COPPER.
4. PLATING: PLATE WITH NON-COMPLIANT, DIMENSION SILVER PREFERRED, DIMENSION 71N OR Sn/Ag/Cu, WITH 50A FLUX, 0.0005" +/- 0.0004" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLAKES ARE ACCEPTABLE.
5. FINISH: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK. BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
6. LEGEND: PCB BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
7. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ART AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
8. WORKSHIP: HOLE DIMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
9. PANEL SIZES: ANY METAL IN BOMBAY AREA INCLUDING PART NUMBER, DATACODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
10. PROCESS CHANGES AND DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

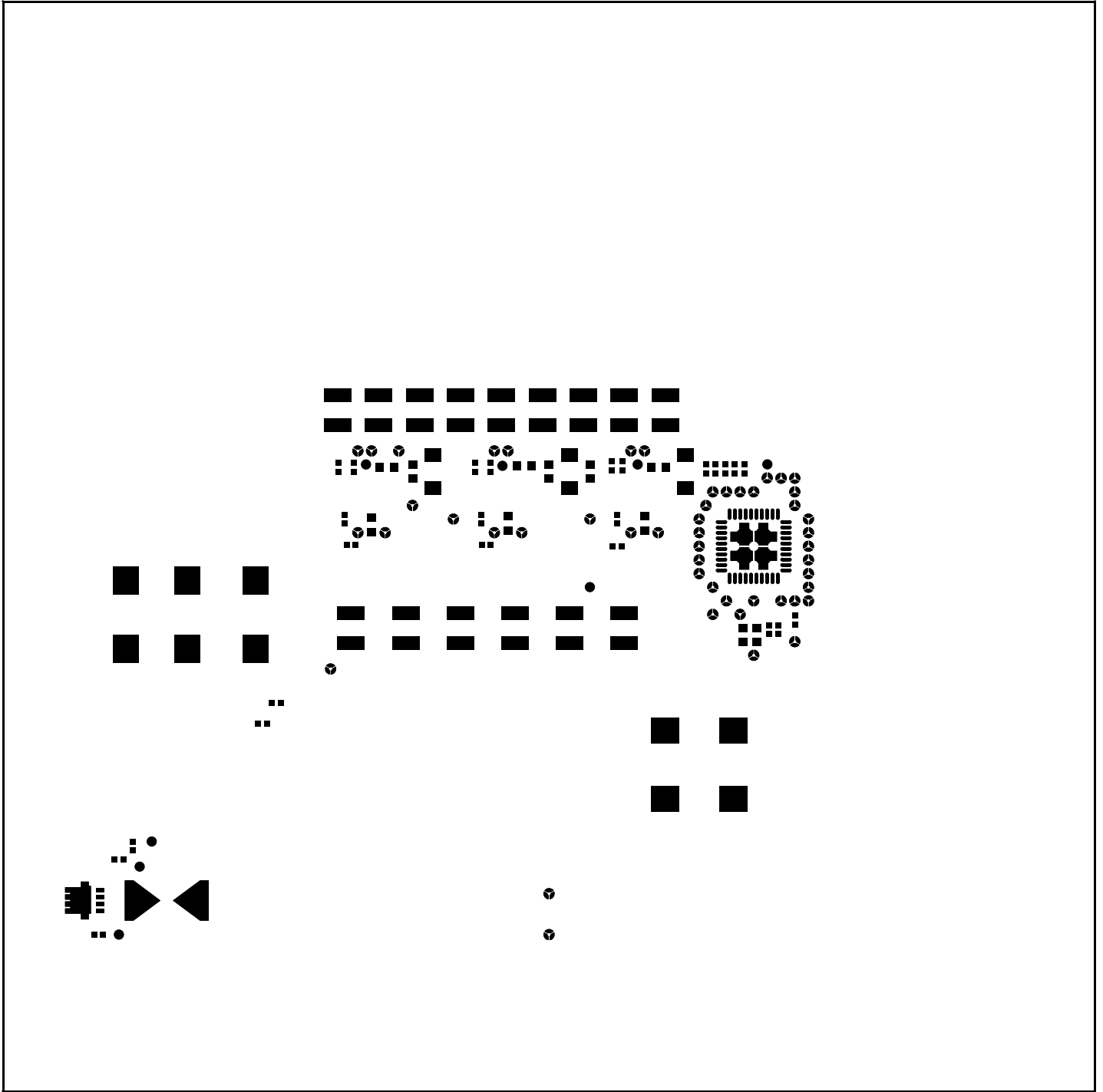


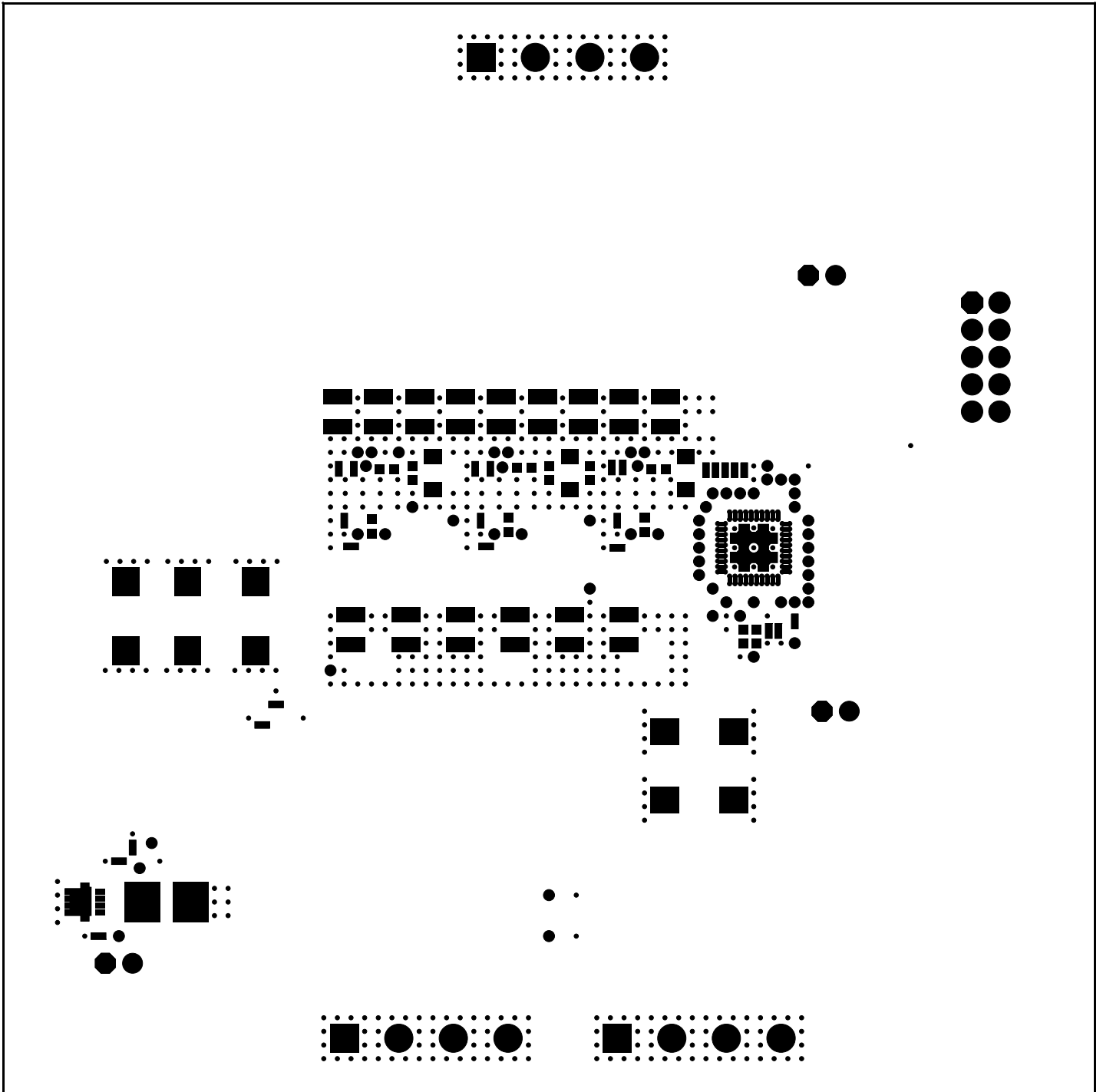
VIEW X-X XX
 SCALE = NONE

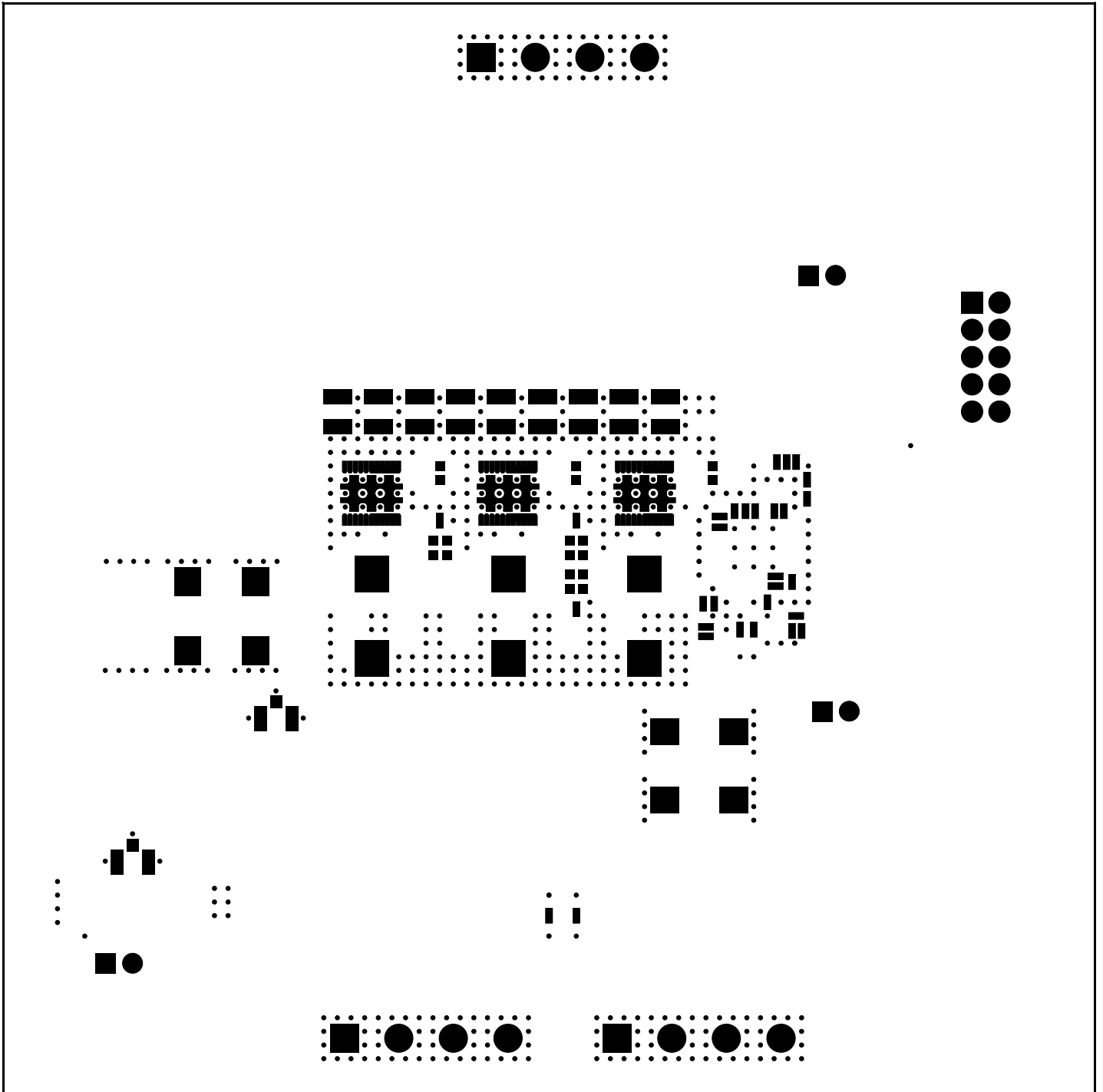
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
o	10.0	+3.0/-3.0	PLATED	523
+	50.0	+3.0/-3.0	PLATED	6
+	55.0	+3.0/-3.0	PLATED	10
△	70.0	+3.0/-3.0	PLATED	12

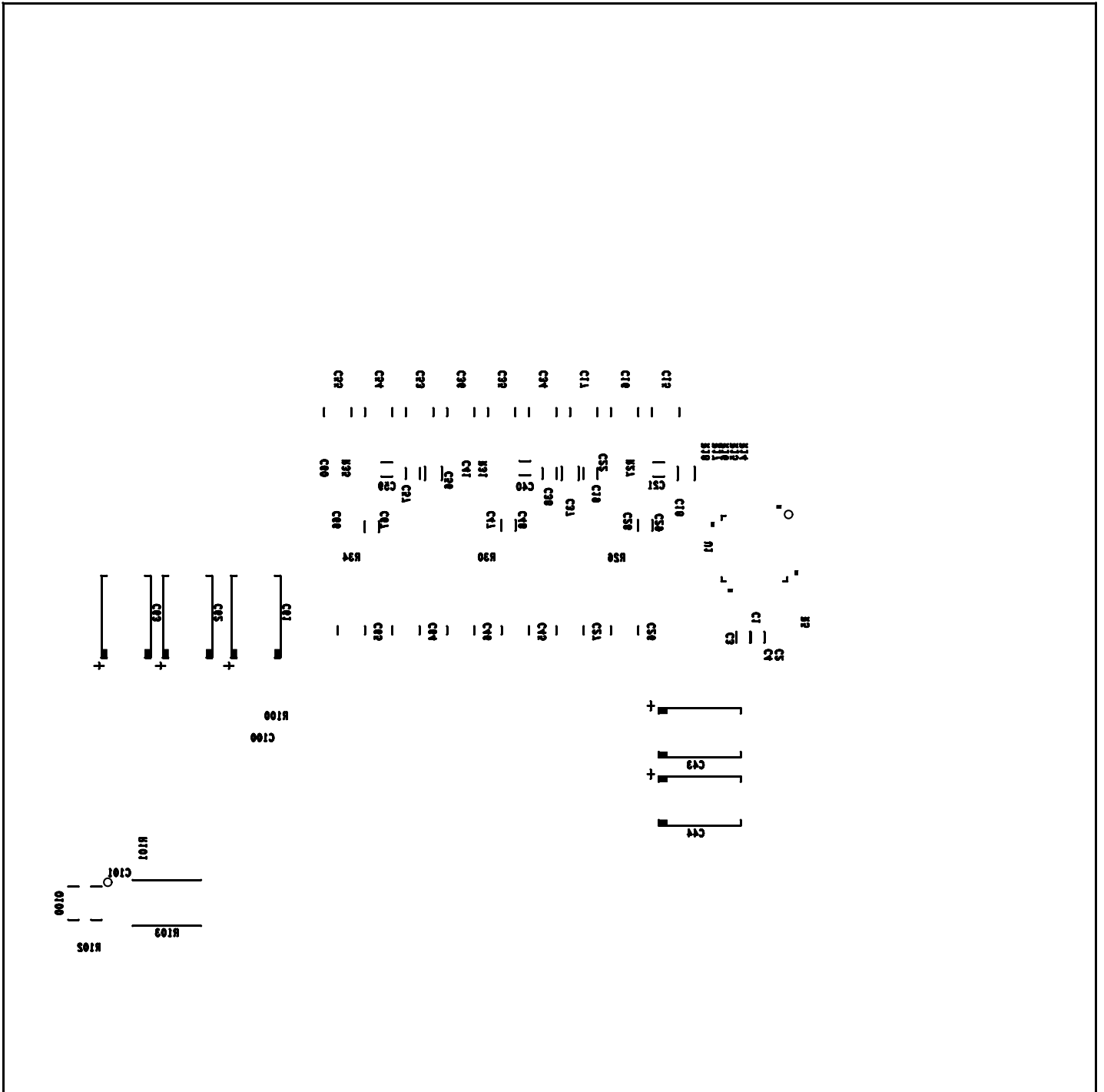






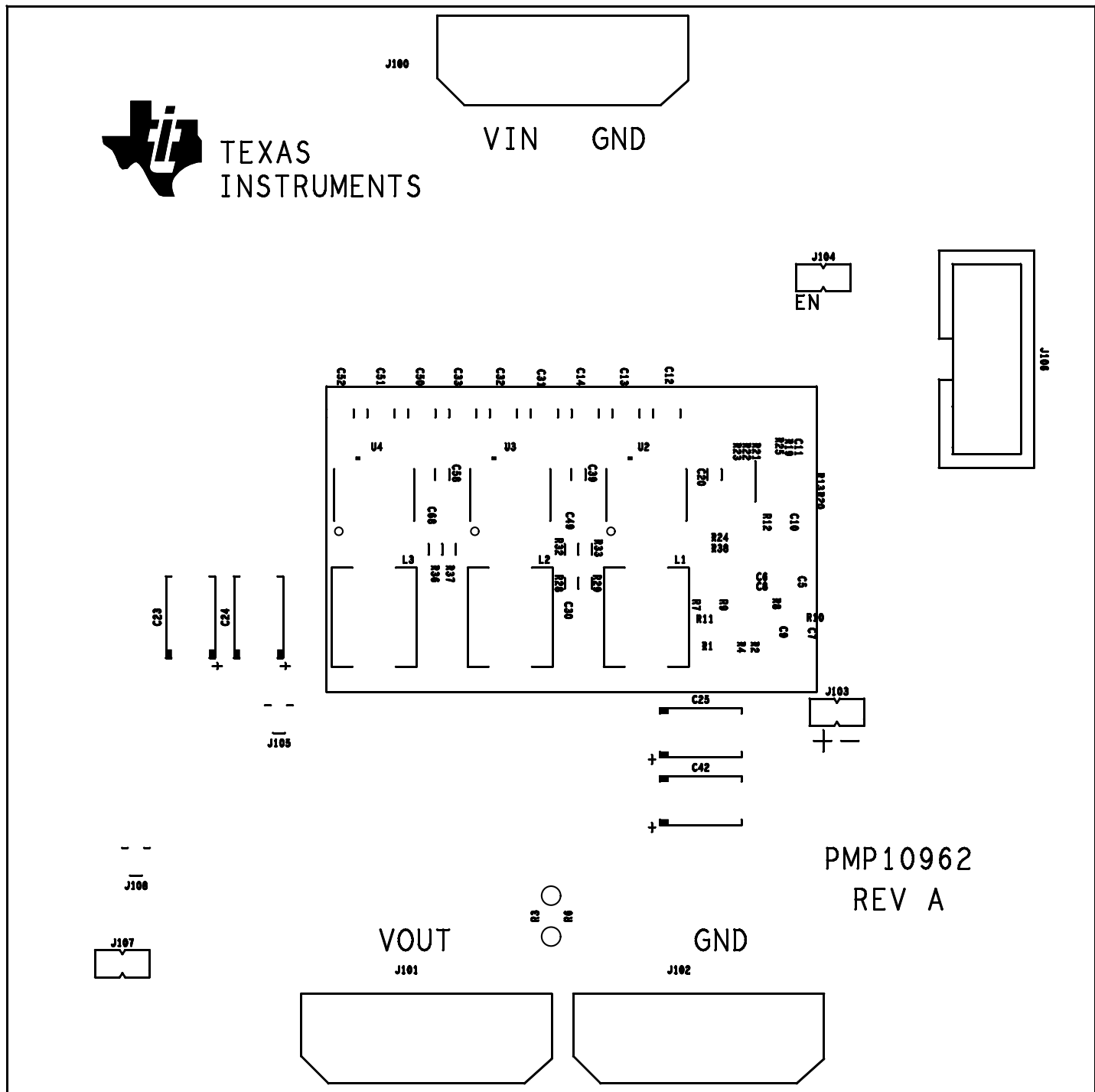


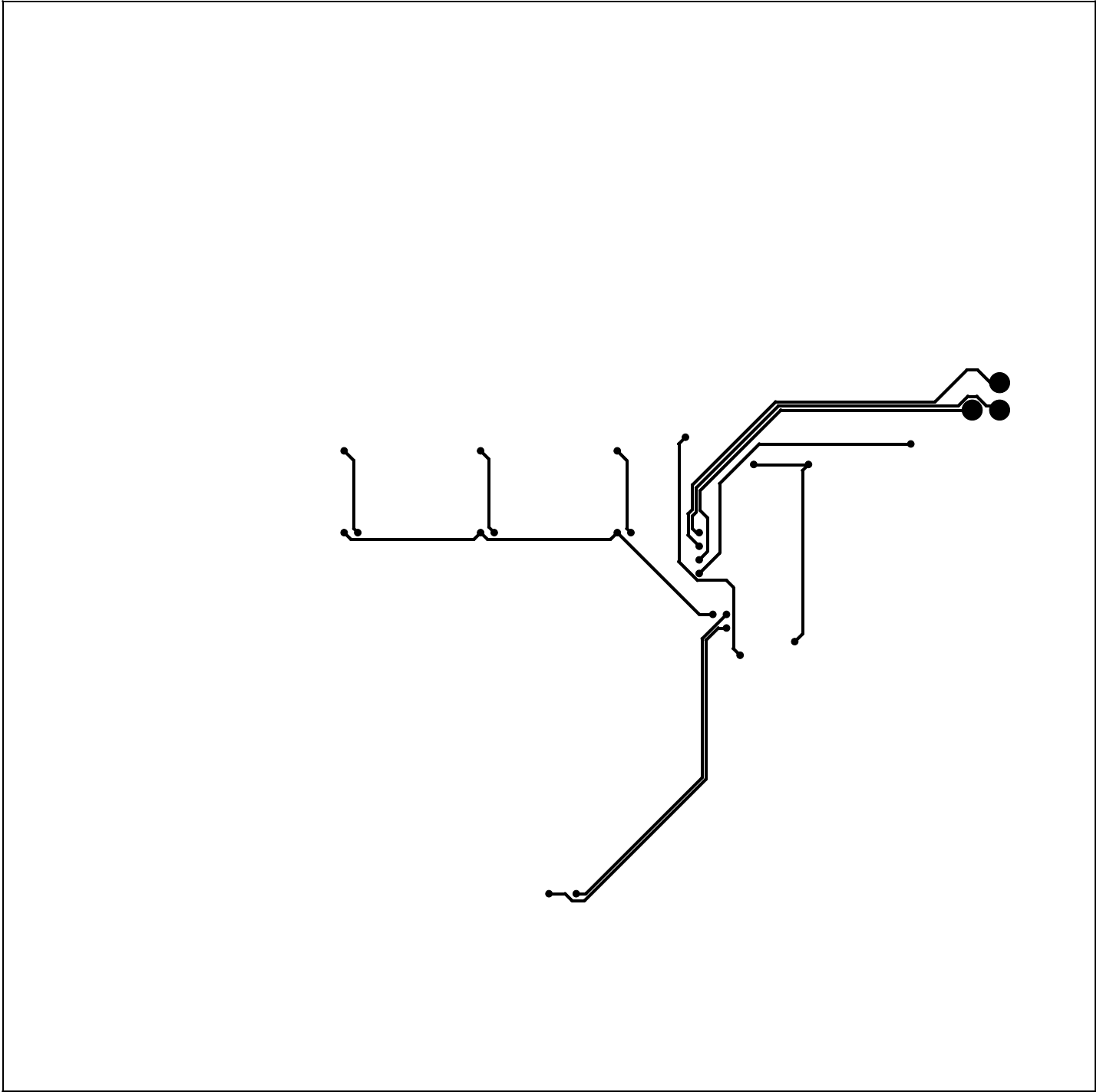


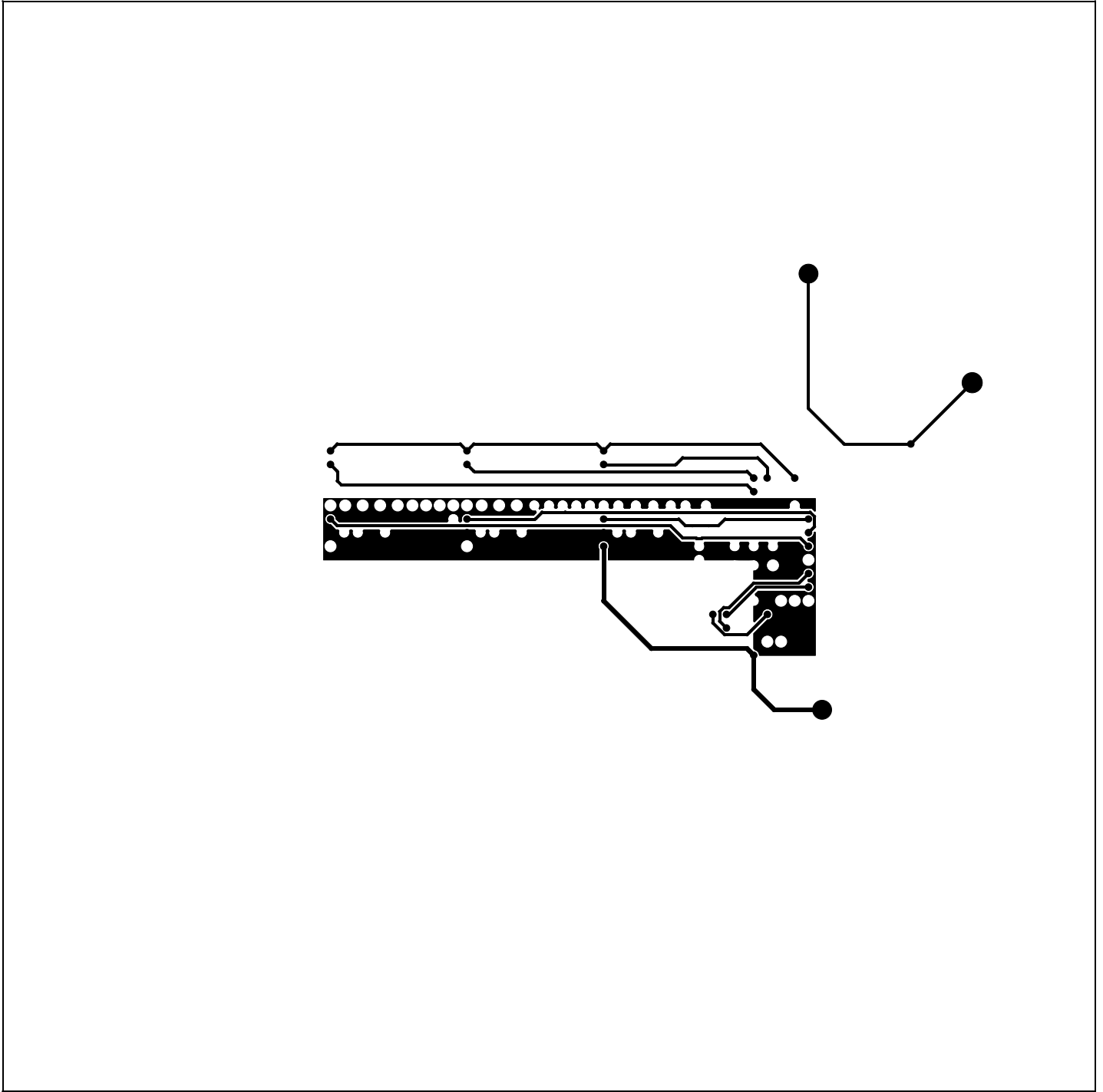


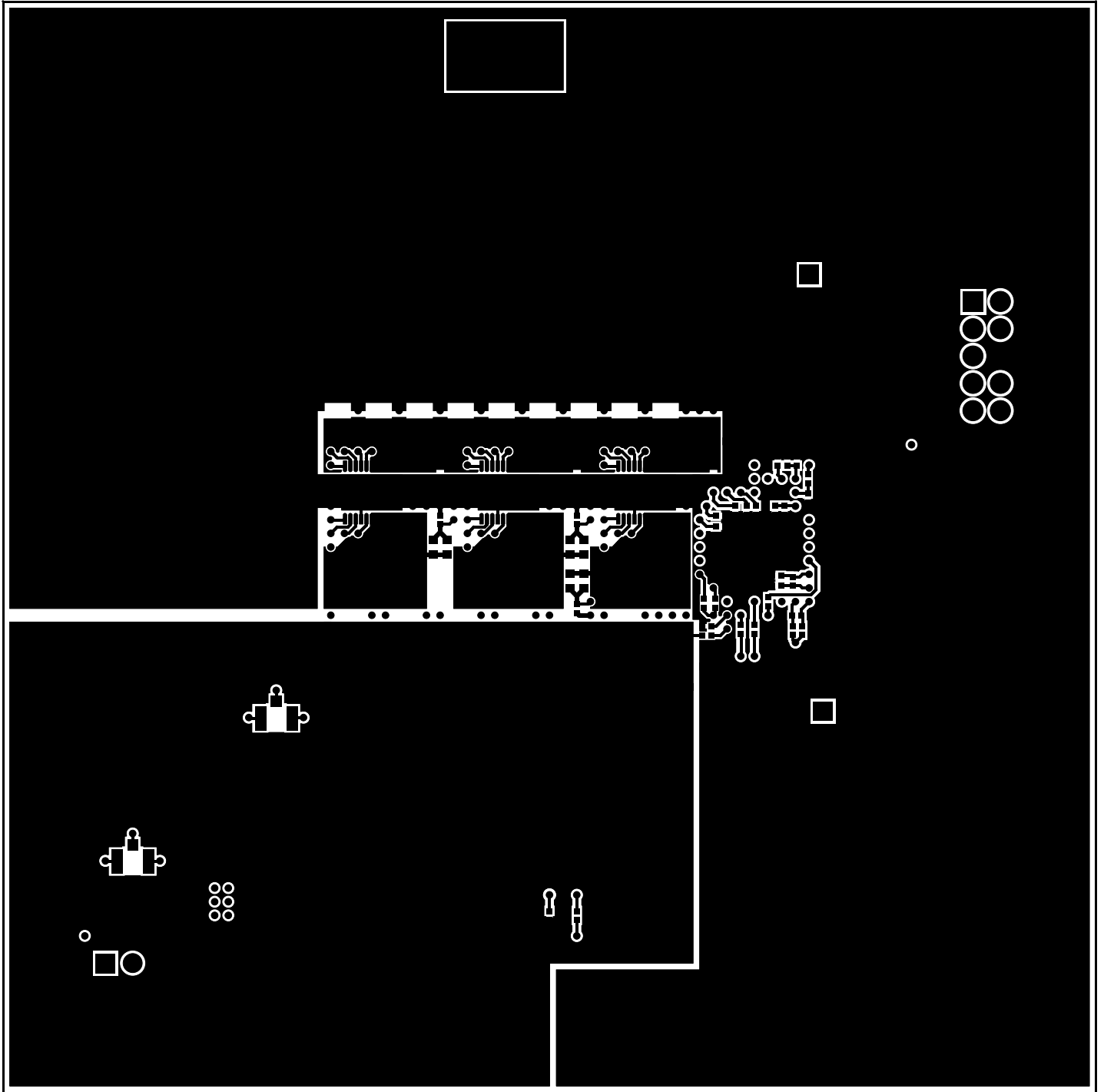


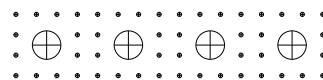
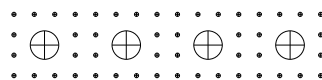
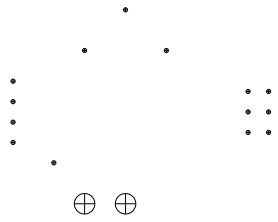
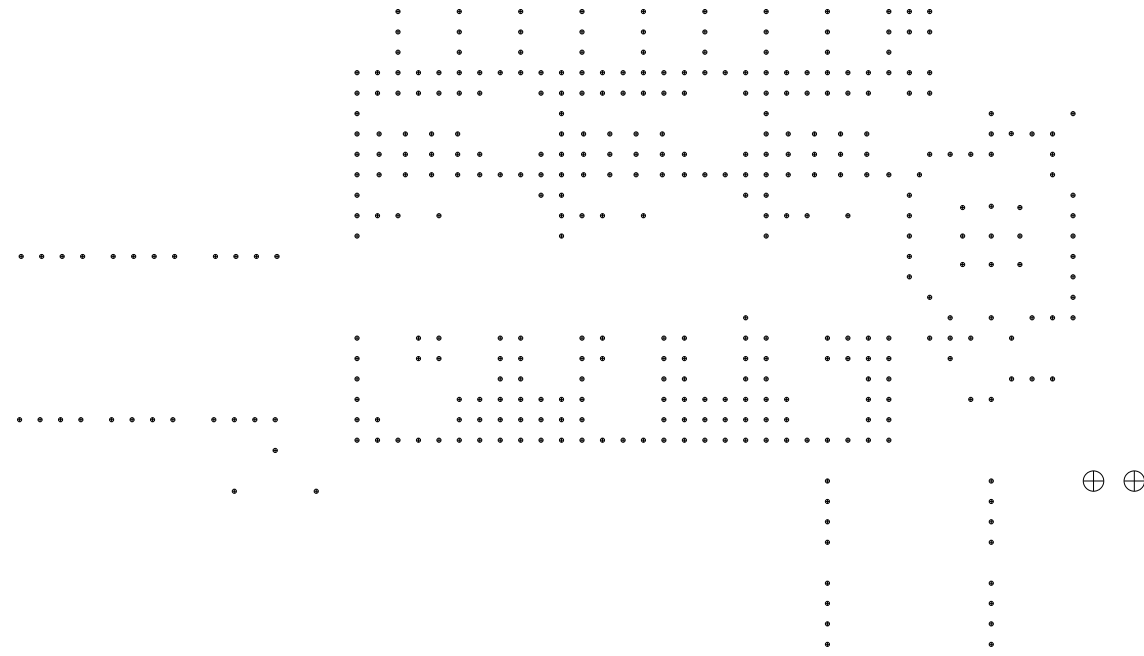
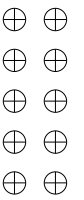
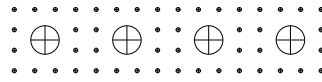
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